Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Ti Ni Ag**

**Bond Pad Size: .004” min**

**Backside Potential: Collector**

**Mask Ref: 003140**

**APPROVED BY:RB DIE SIZE: .100” X .100” DATE: 10/20/21**

**MFG: GENERAL SEMI THICKNESS: .015” P/N:2N4150**

**DG 10.1.2**

#### Rev B, 7/19/02